

S606

Thermal Compound



Features

Good thermal conductivity Easy to assemble High stability Does not harden with time

Applications

Electronic components: IC – CPU – MOS

LED - M/B – P/S – Heat Sink

LCD – TV – Notebook PC – PC Telecom Device – Wireless Hub... etc.

DDR II Module – DVD Applications – Hand-set applications... etc.

Storage

S606 has a self-life of eighteen (18) months from the date of manufacture, as indicated by the lot number, when stored in the original, unopened contained at, or below 25 °C.

Properties

Property	S606	S606B	S606C	TG-S606P	Unit	Test Method
Color	White	White	Grey	White	-	Visual
Thermal Conductivity	3.6	1.8	5	8.0	W/mK	ASTM D5470
Weight Loss	<0.5	<0.5	<0.5	<0.5	%	ASTM E595
Specific Gravity	2.3	2.3	2.3	3.0	g/cm³	ASTM D72
Working Temperature	-40 to180	-40 to180	-40 to180	-40 to 180	°C	-
Volume Resistance	>1012	>1012	>1012	>1012	Ohm-cm	ASTM D257
Standard Package	1 Kg	1 Kg	1 Kg	1Kg	Kg/pot	-



NOTICE: The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own test to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated T-Global Technology Europe and North America's invoice, quotation, or order acknowledgment. We disclaim any and liability incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any process or to manufacture or to use any product in conflict with existing future patents covering any product or material or its use.